

IN THE SUBSTITUTE SPECIFICATION OF APRIL 2002

Please replace the paragraph beginning at page 3, line 8 (as numbered), with:

Referring to Figs. 2a, 2b, and 2c, according to the first embodiment of the invention, the stacked semiconductor chip package 2 comprises a substrate 21, a first chip 22, a plate 23, and a second chip 24. The first chip 22 is mounted on the top surface of the substrate 21 and electrically connects to the substrate 21 by a plurality of electrical leads, e.g. wires. The plate 23 is mounted between the first chip 22 and the second chip 24, and is stacked on the first chip 22. The plate 23 adheres to the first chip 22 by using an adhesive.

Please replace the paragraph beginning at page 3, line 15 (as numbered), with:

The second chip 24 is mounted on the plate 23, and adheres to the plate 23 by using an adhesive. Referring to Fig. 2b, the second chip 24 has two opposed longitudinal sides defining a first length L1. Corresponding to the two longitudinal sides of the second chip 24, the plate 23 has two opposed longitudinal sides defining a second length L2. The second length L2 is large than the first length L1 to expose the opposite longitudinal sides of the plate 23. An overflow adhesive portion 26 is formed between the plate 23 and the second chip 24, and the overflow adhesive portion 26 exposes on the plate 23. That is, the portion of the plate 23 under the second chip 24 is wrapped in the adhesive layer 25, and the overflow adhesive portion 26 is exposed at the corner formed by the plate 23 and the second chip 24 along the longitudinal side of the plate 23. Therefore, the testing instrument can detect the size of the overflow adhesive portion 26 and the thickness of the adhesive layer 25 so as to control the quality of the stacked semiconductor chip package. The adhesion strength between the second chip 24 and the plate 23 can be augmented to raise the reliability of the stacked semiconductor chip package product.